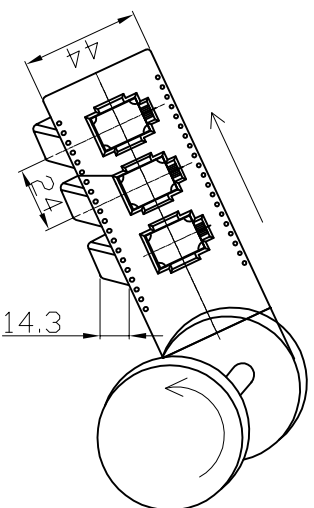
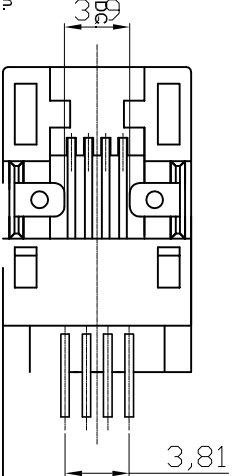


**PC Board Layout**

**Component Side Shown**



**NOTES:**

**ELECTRICAL:**

1. VOLTAGE RATING
2. CURRENT RATING
3. CONTACT RESISTANCE
4. INSULATION RESISTANCE
5. DIELECTRIC STRENGTH

**MECHANICAL:**

1. HOUSING MATERIAL
2. CONTACT MATERIAL
- ④ 3. PLATING

4. OPERATING LIFE
5. PCB RETENTION POST-SOLDER ENVIRONMENTAL:

1. STORAGE
2. OPERATION TEMPERATURE
3. REFLOW SOLDERING TEMPERATURE: 255°C-265°C (5~10 SECONDS).

- : 125 VAC.
- : 1.5 AMP.
- : 35 MILLIOHMS MAX.
- : 1000 MEGOHMS MIN. @ 500 VDC
- : 1000 VAC 60HZ, 1MIN.
- : PA9T UL94V-0, BLACK.
- : PHOSPHOR BRONZE l=0,35mm.
- : 6µ" GOLD ON CONTACT AREA
- : 100-200µ" TIN ON SOLDER AREA
- : ALL OVER 30-50µ" NICKEL.
- : 750 CYCLES MIN.
- : 10 LBS MIN.
- : -40°C TO +85°C.
- : -40°C TO +85°C.
- : 255°C-265°C (5~10 SECONDS).

**RoHS compliant**  
Unit: mm



File No.: E345352

Scale	Free TOLERANCE
.X	±0.20
.XX	±0.15
.XXX	±0.10
DIM	TOL
Angle	±5°

Id.	Modification	Date	Name
④	Update the contact plating	25.08.2015	Amy
③	Update	15.07.2009	Dean
②	Zeichnung überarbeitet	15.11.2007	N.Schulz
①	Neuanlage	24.09.2007	N.Schulz

Date	Name
Drawn 24.09.2007	N.Schulz
Approved 25.08.2015	Amy

**ASSMANN**  
components

Customer-No.	
ASSMANN WSW-No.	A-200040-LP/SMT-B
Drawing-No.	ASS 1051 CO
Replace	rev04
	SHEET

1 2 3 4 5 6 7

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